# Product Change Notification

# 104859 - 00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** asmo.pcn@intel.com

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**Japan Email:** jccb.ijkk@intel.com

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# Product Change Notification

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|---|---|
| **Change Notification #:** | **104859 - 00** |
| **Change Title:** | **Wafer Products, PCN 104859-00, FYI, Std Intermediate Box label Change** |
| **Date of Publication:** | **February 21, 2005** |

## Type of Change Notification:

**FYI -** (For Your Information)

## Key Characteristics of the Change:

Transport Media

## Forecasted Key Milestones:

| | |
|---|---|
| **Date Customer Must be Ready to Receive Post-Conversion Material:** | Mar 14, 2005 |

## Description of Change to the Customer:

Per the Tax, Licensing, and Customs Department, Country of Origin must show be the Silicon Fabrication location, instead of the Assembly site for wafer products. This label change will replace the Std Intermediate Box label for die and wafer products.

The customer will see a difference in the current adhesive label. Please see pictures below. There will be no changes to the affected products.

The new label will follow Intel's stringent quality and reliability standards.

This will improve Intel Corporation's supply flexibility to better serve the customers.

## Customer Impact of Change and Recommended Action:

Dimensions of existing label will remain.

The change involves the Intermediate Box Label for wafer products. The box label will state "FABRICATED IN Country of Origin".

The transition timeline is expected to be completed by March, 2005. During this time current and new labels will be shipped interchangeably and mixed within shipments.

Intel anticipates no impact to customers; however the customer may want to inform their receiving department of this change.

## Products Affected / Intel Ordering Codes:

### Component Product Table

| Product Code | S-Spec | Material Master # |
|---|---|---|
| X28F128K18C115 | S L18V | 851828 |
| X28F128K3C115 | S L774 | 855550 |
| X28F128L30B85 | S L7YS | 865620 |
| X28F128L30T85 | S L7YT | 865621 |
| X28F128L3B100 | S L74Z | 854631 |
| X28F128W18BD60 | S L7CT | 858333 |
| X28F256L18BD85 | S L882 | 867714 |
| X28F256L18BD85 | S S L7T | 863767 |
| X28F256L18TD85 | S L7UN | 863871 |
| X28F256L18TD85 | S L8DV | 869687 |
| X28F640W18BD60 | S L7R8 | 863118 |
| X28F640W30BD70 | S L7XE | 865210 |
| X28F640W30TD80 | S L7US | 863886 |
| X80296SA |  | 865220 |
| X80C18XEAXL |  | 862939 |
| X80C18XEB |  | 862940 |
| X80C196KB |  | 867431 |
| X87C196KC | S W99 | 853833 |
| X87C196KD | S W99 | 825922 |
| X87C51FC | S W99 | 852435 |

## Reference Documents / Attachments:

**Document:** **Location #:**

**Current Label**

(P) CUST PROD:

(1B) BOX: XX000053

(V) SUPPLIER: 04195 (M): (C):

MAX REFLOW 260 °C
TEMP
LEVEL3 HOURS 168
BAG SEAL DATE24JUN04

(1P) IPN: INTEL PRODUCT NAME

(S) SPEC: S SPEC (30P) MM#: 999999

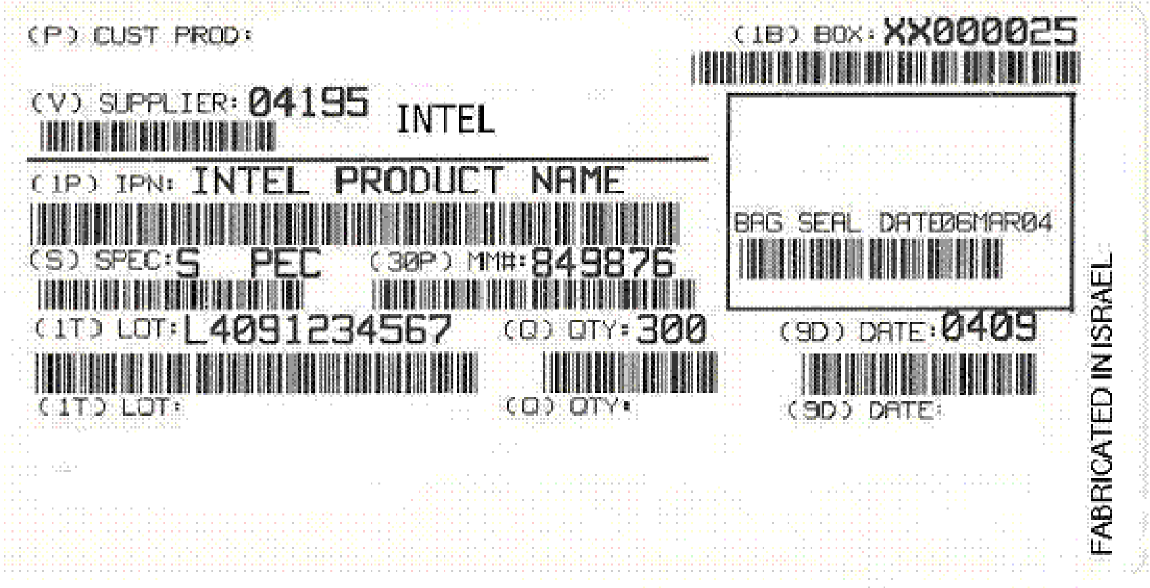
(1T) LOT: U4261234567 (Q) QTY: 2000 (9D) DATE: 0426

(1T) LOT: (Q) QTY: (9D) DATE:

Pb-FREE=e1

ASSEMBLED IN PHILIPPINES

**New Label**



(P) CUST PROD:

(1B) BOX: XX000025

(V) SUPPLIER: 04195 INTEL

(1P) IPN: INTEL PRODUCT NAME

(S) SPEC: S PEC (30P) MM#: 849876

BAG SEAL DATE06MAR04

(1T) LOT: L4091234567 (Q) QTY: 300 (9D) DATE: 0409

(1T) LOT: (Q) QTY: (9D) DATE:

FABRICATED IN ISRAEL

## PCN Revision History:

| **Date of Revision:** | **Revision Number:** | **Reason:** |
|---|---|---|
| February 21, 2005 | 00 | Originally Published PCN |